

AF/289!
11/2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Nguyen et al.

Attorney Docket No.:
NSC1P131X1/P04314P01

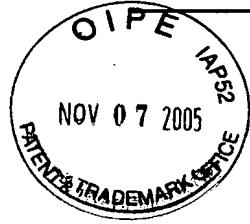
Application No.: 10/080,913

Examiner: Farahani, Dana

Filed: February 21, 2002

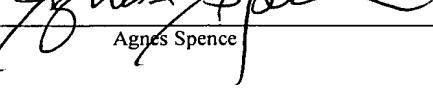
Group: 2891

Title: METHOD AND APPARATUS FOR
FORMING AN UNDERFILL ADHESIVE LAYER



CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on November 3, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450

Signed: 

Agnes Spence

**INFORMATION DISCLOSURE STATEMENT
AFTER FINAL ACTION OR NOTICE OF ALLOWANCE
(37 CFR §§ 1.56 AND 1.97(d))**

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of non-U.S. references are attached, may be material to examination of the above-identified patent application. Applicants identify these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make this citation of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that this reference indeed constitutes prior art.

This Information Disclosure Statement is being filed after the mailing date of final action under §1.113 or a notice of allowance under §1.311, but before payment of the issue fee.

11/08/2005 MWOLDGE1 00000065 500388 10080913

01 FC:1806 180.00 DA

Accompanying this Information Disclosure Statement is the fee set forth in 37 CFR 1.17(p).

The undersigned hereby states:

that each item of information contained in the Information Disclosure Statement was first cited in a communication from a foreign patent office in a counterpart foreign application no more than three months prior to the filing of the Information Disclosure Statement, or

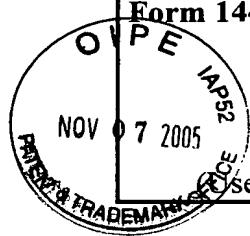
that no item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and to the knowledge of the person signing the certification after making reasonable inquiry, no item of information contained in the Information Disclosure Statement was known to any individual designated in § 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.

The Commissioner is hereby authorized to charge the required fees (Information Disclosure Fee \$180.00) to Deposit Account 500388 (Order No. NSC1P131X1).

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP

James W. Rose
Registration No. 34,239

P.O. Box 70250
Oakland, CA 94612-0250
(650) 961-8300


Form 1449 (Modified)
**Information Disclosure
Statement By Applicant**

(Use Several Sheets if Necessary)

 Atty. Docket No.
NSC1P131X1/P04314P01
Applicant:
Nguyen et al.
Filing Date
February 21, 2002

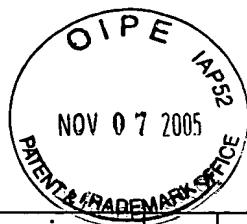
 Application No.:
10/080,913
Group
2891

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A	5,329,423	07/12/94	Scholz			04/13/93
	B	5,495,439	02/27/96	Morihara			09/07/94
	C	5,500,534	03/19/96	Robinson et al.			03/31/94
	D	5,736,456	04/07/98	Akram			01/17/96
	E	5,767,010	06/16/98	Mis et al.			11/05/96
	F	5,773,359	06/30/98	Mitchell et al.			12/26/95
	G	5,872,633	02/16/99	Holzapfel et al.			02/12/97
	H	5,925,936	07/20/99	Yamaji			02/26/97
	I	5,937,320	08/10/99	Andricacos et al.			04/08/98
	J	5,977,632	11/02/99	Beddingfield			02/02/98
	K	6,171,887	01/09/01	Yamaji			05/04/99
	L	6,307,269	10/23/01	Akiyama et al.			07/10/98
	M	6,316,528	11/13/01	Iida et al.			07/08/99
	N	6,327,158 B1	12/04/01	Kelkar et al.			01/15/99
	O	6,352,881 B1	03/05/02	Nguyen et al.			07/22/99
	P	6,372,547	01/10/02	Nakamura et al.			03/11/98
	Q	6,391,683	05/21/02	Chiu et al.			06/21/00
	R	6,455,920	09/24/02	Fukusawa et al.			09/25/98
	S	6,486,562	11/26/02	Kato			06/07/00
	T	6,507,118	01/14/03	Schueller			07/14/00
	U	6,818,550	11/16/04	Shibata			07/11/02
	V	6,822,324	11/23/04	Tao et al.			01/28/03

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	W							
	X							
	Y							
	Z							
	A1							



Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	A2	“Polymer Collar WLP™, Wafer Level Package Family”, © 2002, downloaded from www.kns.com/prodserv/PDFS/FCD/polymer_collar.pdf , 2 pages.
	A3	“Presenting Polymer Collar WLP™ - A New Wafer Level Package for Improved Solder Joint Reliability”, © 2002, downloaded from www.kns.com/prodserv/flipchip/pdf/PC_ad.pdf , 1 page.
	A4	Barrett et al., Kulicke & Soffa, “Polymer Collar WLP™ - A New Wafer Level Package for Improved Solder Joint Reliability”, © 2002, downloaded from www.kns.com/resources/articles/PolymerCollar.pdf , 9 pages.
	A5	Bogatin, Eric, “All Dressed Up and Nowhere to Go”; <i>Semiconductor International</i> , May 1, 2002, downloaded December 23, 2003, from www.reed-electronics.com/semiconductor/index.asp?layout=article&articleid=CA213812&rid=0&rme=0&cfid=1 , 2 pages.
	A6	Nguyen et al., “Effect of Underfill Fillet Configuration on Flip Chip Package Reliability”, SEMI® Technology Symposium: International Electronics Manufacturing Technology (IEMT) Symposium, SEMICON® West 2002.
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.